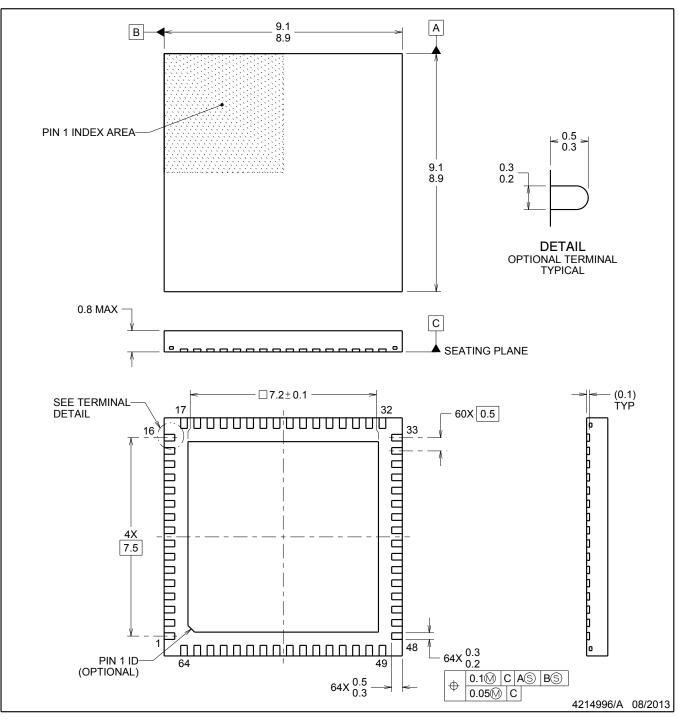
# PACKAGE OUTLINE



### WQFN - 0.8 mm max height

WQFN



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



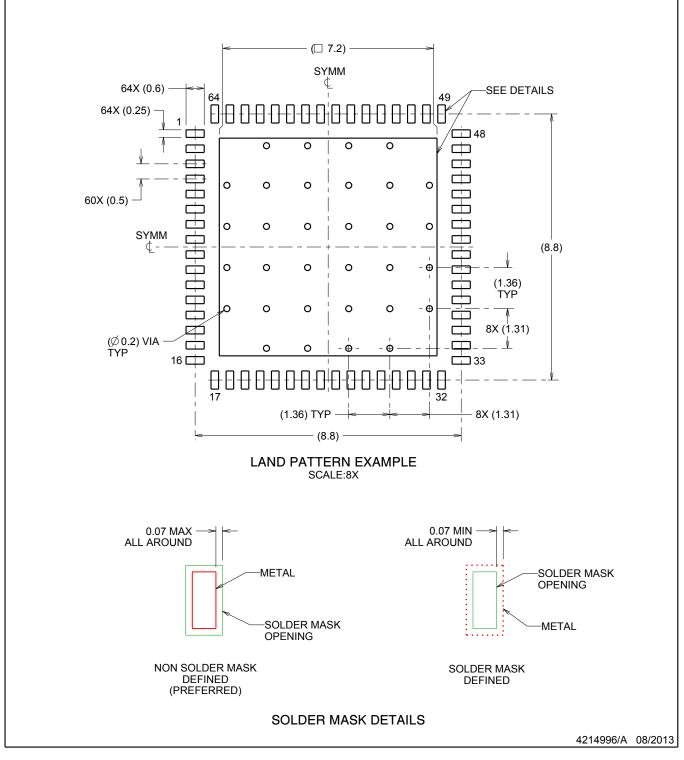
### **NKD0064A**

### NKD0064A

# EXAMPLE BOARD LAYOUT

#### WQFN - 0.8 mm max height

WQFN



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).

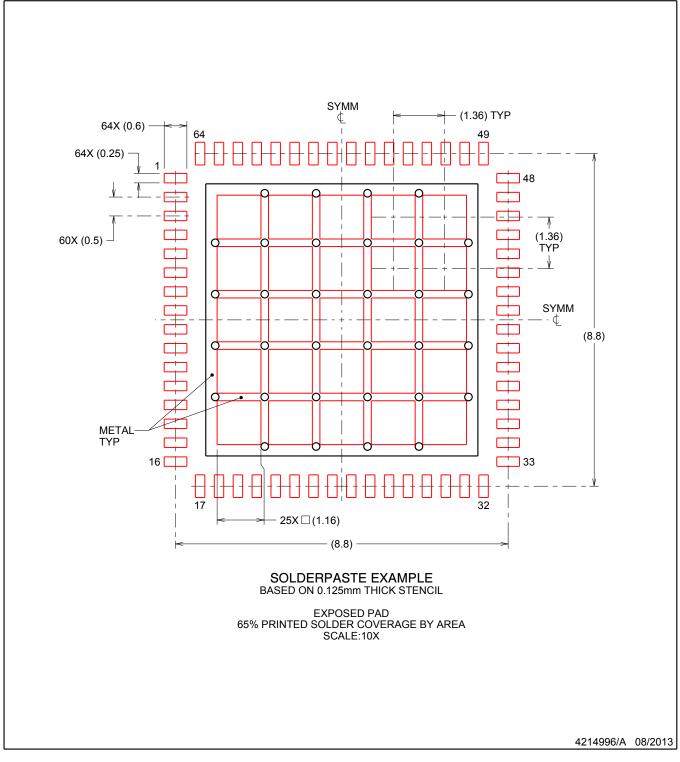


### **NKD0064A**

# EXAMPLE STENCIL DESIGN

#### WQFN - 0.8 mm max height

WQFN



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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